

AGENDA
P-2.5 COMMITTEE FOR TANTALUM, NIOBIUM, ALUMINUM CHIP
CAPACITORS
WEDNESDAY, Sept 29, 2010
Austin, Tx.

I. COMMITTEE ORGANIZATION AND PROCEDURE

- 1. Membership and attendance –**
- 2. Approval of agenda –**
- 3. Approval of minutes –**
- 4. Correspondence -**

II. OLD BUSINESS

- 1. Reports**
 - a. S-1 Passive Component Steering Committee –**
 - b. Government Specifications and standards (DSCC representative/Tech America) –**
 - c. AEC Q200 Subcommittee –**
- 2. Review of Current Active Specifications**
 - a. 535BAAC molded Chip Specification**
 - b. EIA – 809 Applications Guide**
 - c. EIA/IS- 717 Qualification Spec**
 - d. EIA-757 Visual and Mechanical Guide**
 - e. EIA-953 Polymer Tantalum Specifications**
- 3. Review of Current PNs to stay Active**
 - a. PN 5138 – MicroMini Design**
 - b. PN 5137 – Facedown Design**
 - c. PN 5100 – EIA-757 Revision**
 - d. PN 5098 – EIA-809 Revision**
- 4. Review of Current Component Bulletins**
 - a. Shelf life of tantalums**
- 5. Status of Archive Specs:**
 - a. 535BAAE – Molded Ta Chips Low ESR**
 - b. 535BAAD – Molded Ta Chips Protected, Extended Range**
- 7. Draft of paragraphs to describe the contents of active specs.**

III. NEW BUSINESS

1. List of proposed specification actions

- a. Specs we need to revise**
- b. other specs we need to have**

2. Component Bulletins

- a. New CB's needed?**

3. Environmental Compliance Benchmarking

- a. Annual 3rd party test reports for banned and restricted substances.**
- b. Materials declarations using IPC 1752, Compliance Connect, IMDS.**
- c. BOM level environmental compliance system.**

4. Other New Business -

IV. ADJOURNMENT –